

DUAL DAMASCENE ANTI-FUSE WITH VIA BEFORE WIRE

ABSTRACT OF THE DISCLOSURE

5 An interconnect structure in which a patterned anti-fuse  
material is formed therein comprising: a substrate having  
a first level of electrically conductive features; a  
patterned anti-fuse material formed on said substrate,  
wherein said patterned anti-fuse material includes an  
opening to at least one of said first level of  
10 electrically conductive features; a patterned interlevel  
dielectric material formed on said patterned anti-fuse  
material, wherein said patterned interlevel dielectric  
includes vias, as least one of said vias includes a via  
space; and a second level of electrically conductive  
features formed in said vias and via spaces.